

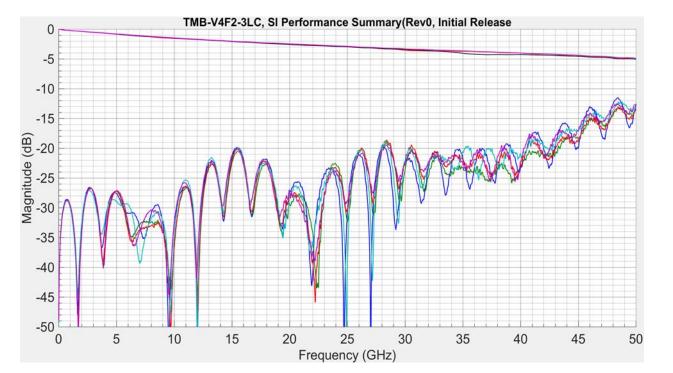
# **Test and Measurement Performance Report**

Part Number TMB-V4F2-3LC

(2.4 mm Vertical Launch CPW Solderless Precision Connector) **Distribution**: *Internal & External Use* 



## SI Performance Summary (Attenuation & Reflections, Single-Ended)



\* 10 connectors are shown, measured in pairs. (5 measurements) For further details regarding testing setup, configurations please see the rest of the report.

REVISION:	ECN INFORMATION:	TITLE: 2.4 mm Vertical Launch CPW			SHEET No.
1	EC No: N/A	Solderless Precision Connector		<b>1</b> of <b>8</b>	
	DATE: 04/ 21 / 2020	(TMB-V4F2-3	LC)		1010
DOCUMENT NUMBER:		SI ENGINEER:	DESIGN ENGINEER ENGINEERING MANA		MANAGER
RSI- TMB_V4F2_3LC		R.Stavoli	P. Volkov	E.Soubh	
			TEM	LATE FILENAME: SPM[S	SIZE_A](V.1).DOC

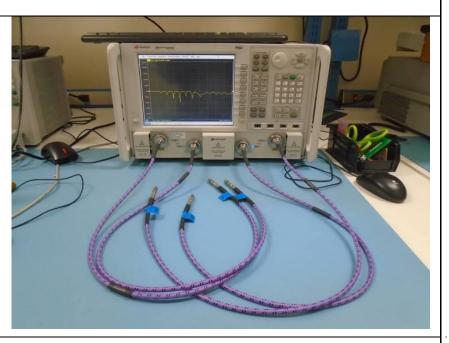


### 1.0 TEST SETUP AND DUT

### Equipment, fixtures, and methods

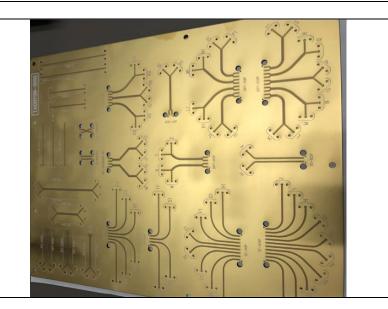
Test method: All data measured from test PCB shown below and a N5227A PNA Network Analyzer

- Calibration was performed up to the
   2. 4mm adapters using calibration kit:
   85056B
- Data was swept from 10 MHz to 50GHz for 5000 points
- Data averaging was turned off.
- Data is not dembedded and includes the board trace/transition and two RF vertical launch CPW precision connectors



### Assembly Description

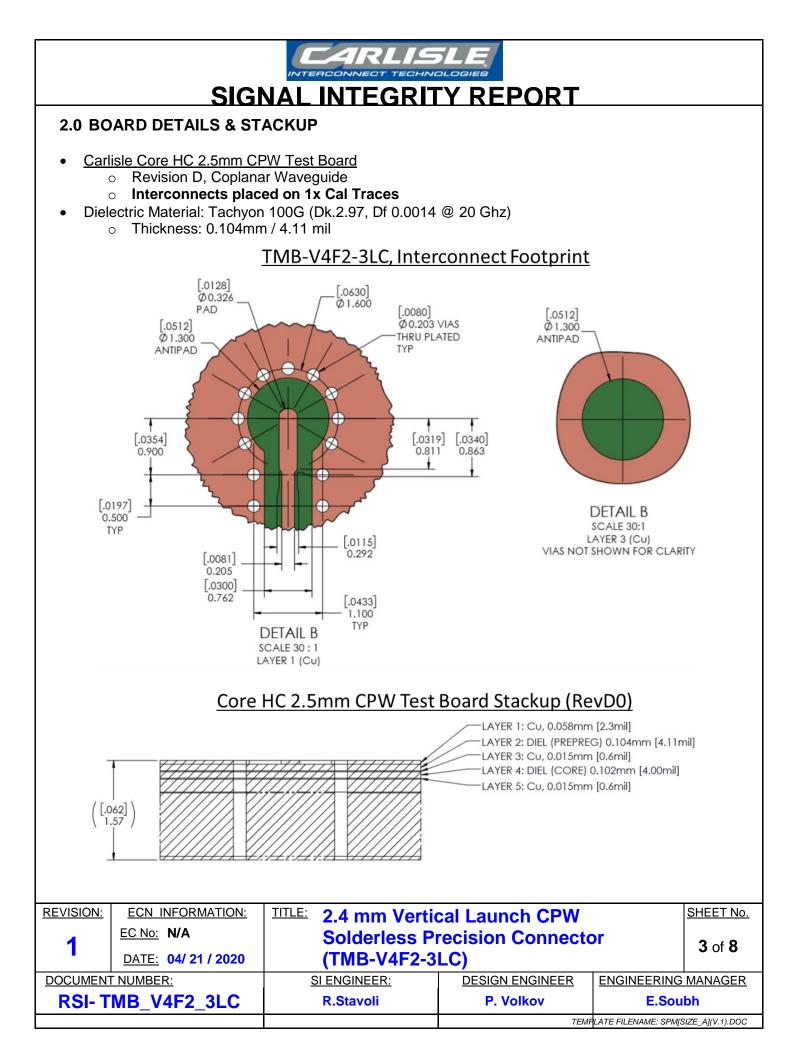
- T&M PN: TMB-V4F2-3LC
- Carlisle DUT PCB: Core HC 2.5mm CPW Test Board (Rev D0)
- Measured on: 1x Cal Trace (SE-1xCal+)
- Port 1: 2.4mm vertical mount CPW
- Port 2: 2.4mm vertical mount CPW



Testing	Samples:

10 Samples	<ul> <li>5 THRU Measurements (5 Channels = 10 samples) -&gt; -Single-Ended</li> </ul>
5 Channels	

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1	<u>EC No:</u> <b>N/A</b>	Solderless Precision Connector		<b>2</b> of <b>8</b>	
	DATE: 04/ 21 / 2020	(TMB-V4F2-3	LC)		2010
DOCUMENT NUMBER:		<u>SI ENGINEER:</u>	DESIGN ENGINEER ENGINEERING MANA		MANAGER
RSI- TMB_V4F2_3LC		R.Stavoli	P. Volkov E.Soubh		bh
TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC			SIZE_A](V.1).DOC		





## SIGNAL INTEGRITY REPORT

#### C) PCB FINISH

#### 1. Surface Protective Plating

- a. All exposed copper on the outer layers shall be plated with a protective surface finish.
- b. All exposed pads, edge fingers and plated through holes shall be ENIG with thickness listed in Table 2.

**Table 2: Protective Plating Thickness** 

Nickel		Immersion Gold	
μm (microinch)		µm (microinch)	
Min.	Max.	Min.	Max.
2.5 (100)	13(512)	0.051 (2)	0.2032 (8)

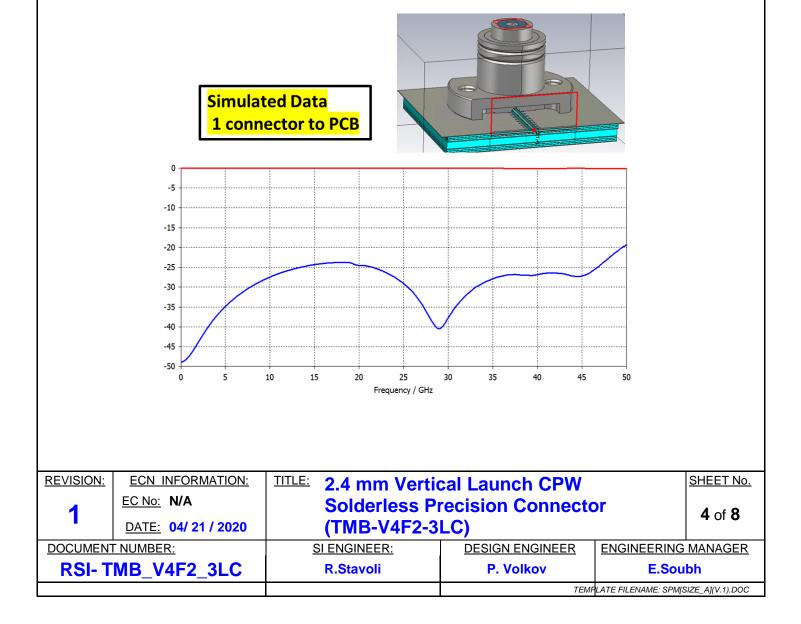
#### 2. Solder Mask

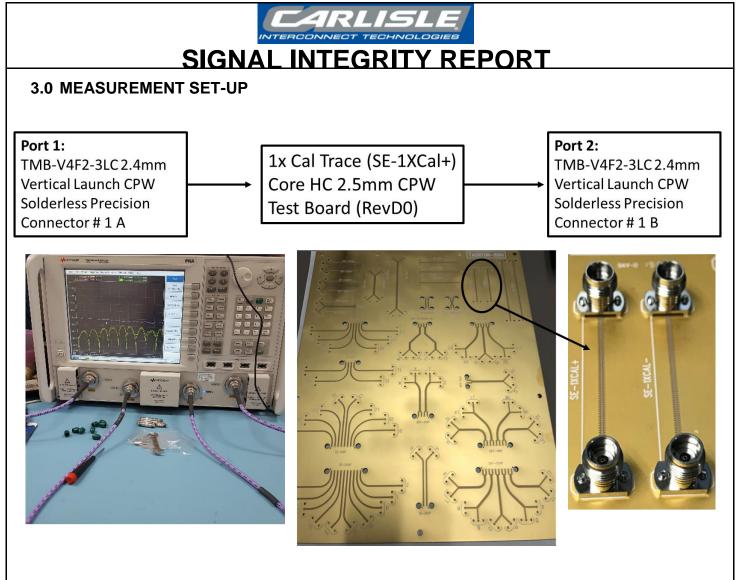
Apply an LPI solder mask to both sides of the board, the solder mask color is defined in the table.

PCB PN	Soldermask color
NA	Green

#### 3. Silkscreen

Silkscreen shall be permanent, non-conductive ink. There shall be no silkscreen on any solderable component pad. Color: White





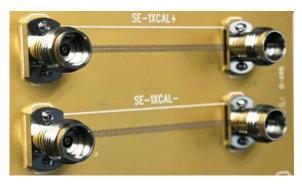
Measurements are not dembedded and include the two 2.4mm vertical launch CPW solderless precision connectors, and the PCB (transition, traces)

REVISION:	ECN INFORMATION:	<b>TITLE:</b> 2.4 mm Vertical Launch CPW			SHEET No.
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			TEMF	LATE FILENAME: SPM[S	SIZE_A](V.1).DOC



# SIGNAL INTEGRITY REPORT

4.0 SIGNAL INTEGRITY RESULTS (CIT: CORE HC 2.5MM CPW PCB, 1X CAL TRACE)



Insertion Loss (S21), 10 connectors measured, 5 measurements

